

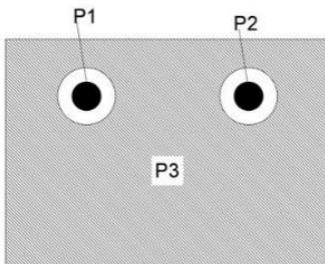
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

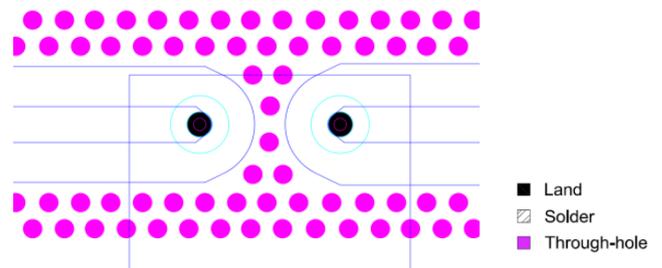
NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)@FC	3000			2.0
	Insertion Loss (dB)@BW	2000-4000			3.0
	Insertion Loss (dB)@+/-100MHz from the filter edges	1900/4100			5.0
2	VSWR	2000-4000			2.0
3	Attenuation (dB)	@1800	25		
		@1500	35		
		@fo+2000	35		
		@fo+3000	60		
4	In/Output Impedance (Ω)		50		
5	Permissible Input Power (W)				1
Operating & Storage Condition (Component)					
Operation Temperature Range: -40°C ~ +85°C					
Storage Temperature Range: -40°C ~ +85°C					
Storage Condition before Soldering (Included packaging material)					
Storage Temperature Range: +5 ~ +40 °C					
Humidity: 30 to 70% relative humidity					

Construction



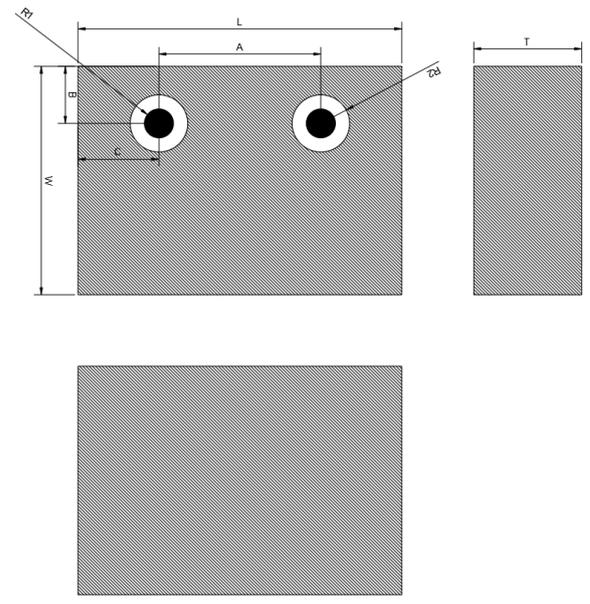
PIN	Connection
1	Input
2	Output
3	GND

Mounting Considerations



Unit: mm
Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	4.5 ± 0.25
	W	3.2 ± 0.25
	T	1.5 ± 0.20
	A	2.25 ± 0.2
	B	0.80 ± 0.15
	C	0.20 ± 0.10
	R1	0.2 ± 0.10
	R2	0.40 ± 0.10

Typical Electrical Characteristics (T=25°C)

